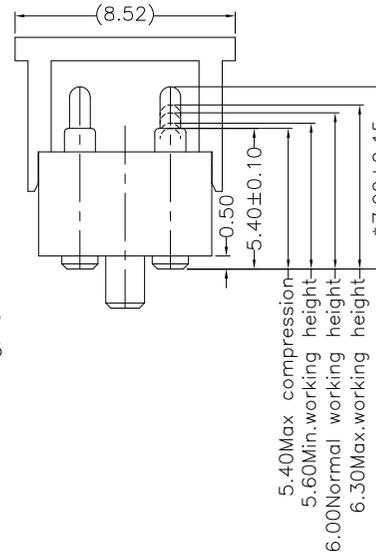
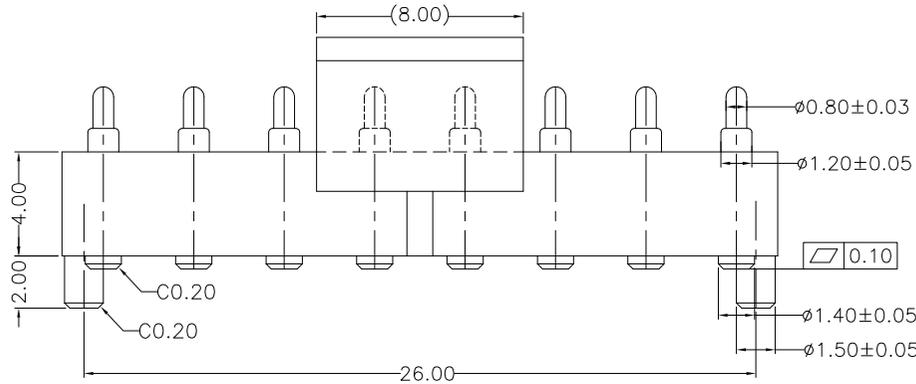
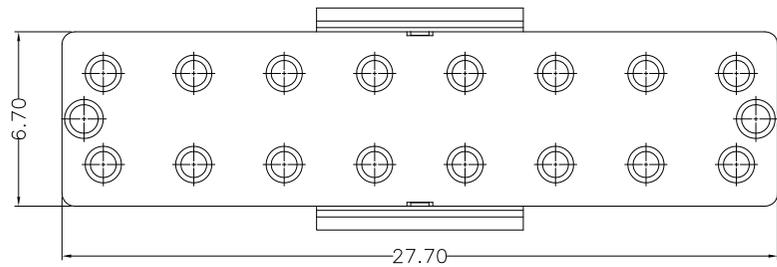


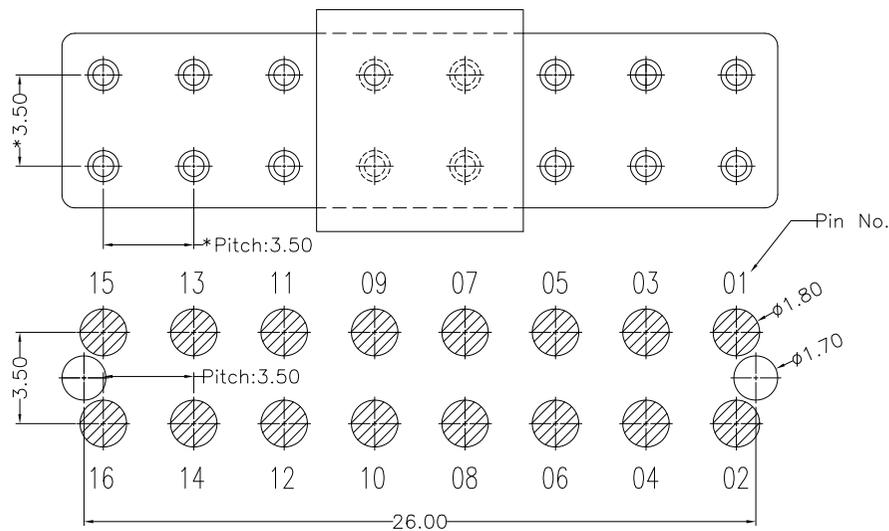
# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2024/12/09	Wu Zonlin



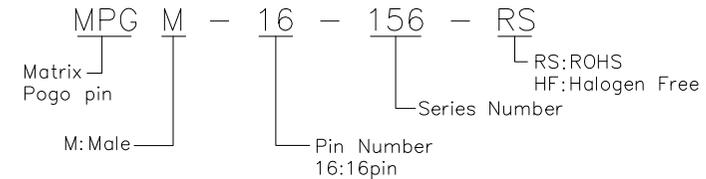
**Notes:**

- Material**  
 Plunger&Barrel: Lead free Brass , Plated Gold flash(1u"min.) over 50-120u"Ni  
 Spring: SUS304  
 Housing: PA9T Black UL94 v-0  
 CAP: PA9T Black UL94 v-0
- Mechanical**  
 Normal Spring force: 100g±15g at working height  
 Durability: 10,000Cycles min
- Electrical**  
 Rated Current&Voltage: DC 12 V, 2.0A  
 Contact Resistance: 100mohm max at working height (quiescence)
- Operating Temperature: -40 to +85°C**  
 Humidity Range: 10%RH to 90%RH  
 Solder Temperature: 260°C±5°10s±2s  
 Salt Spray: 24H, No Corrosion  
 Lead free , RoHS compliant
- Packing:Reel & Carrier**
- To ensure the best usage, please operate it based on the working height  
 Based on the engineering drawings , shall not exceed the min.working height
- "\*" is the key dimensions.



RECOMMENDED PCB LAYOUT  
Tolerance: ±0.05mm

MATRIX PART NO:



Matrix Electronics Co., Ltd

<b>TOLERANCE:</b> 0°6      ±0.10mm >6°30    ±0.20mm >30°120   ±0.30mm >120      ±0.50mm ANGLE    ±5°	<b>DESIGN BY :</b> Wu Zonlin	<b>DATE :</b> 2024/12/09	<b>PART NAME:</b> Pogopin conn	
	<b>CHECKED BY:</b> Hanson Huang	<b>DATE :</b> 2024/12/09	<b>PART NO.</b>	MPGM-16-156-RS
 <b>UNIT: mm [inch]</b>	<b>APPROVED BY1:</b> Richard Hsieh	<b>DATE :</b> 2024/12/09	<b>MOLD NO.</b>	NA
	<b>SCALE:1:1</b> <b>SIZE:A4</b>	<b>APPROVED BY2:</b> Richard Hsieh	<b>DATE :</b> 2024/12/09	<b>DRAW NO.</b> <b>SHEET NO.</b> 1 OF 1